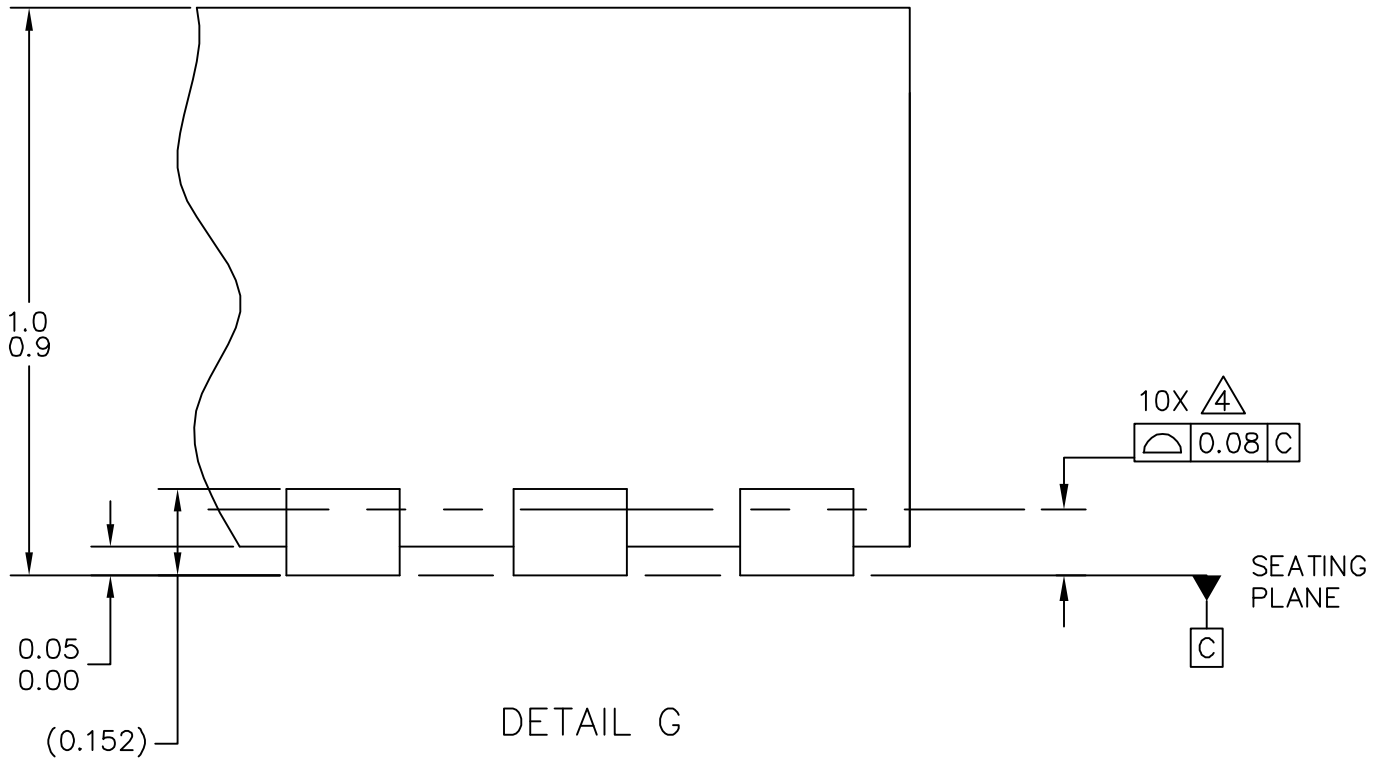


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TITLE: DFN-COL, 2 X 2 X 0.95, 0.4 PITCH, 10 TERMINAL	DOCUMENT NO: 98ASA00301D	REV: C
	STANDARD: NON-JEDEC	
	SOT1615-2	20 OCT 2016



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO ALL TERMINALS.

5. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURE BETWEEN 0.15 AND 0.25 FROM THE TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THIS DIMENSION SHALL NOT BE MEASURED IN THE RADIUS AREA.

6. PIN 1 ID ON TOP WILL BE LASER MARKED.

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